664LF BOM-style material declaration. BI Technologies Corporation **9/9/2010**

No content here is banned per E.U. R.o.H.S.. Average mass of 664LF thin film network is 77 milligrams each. Prepared by Eric Arnold (714) 447-2565
Weights above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	5.42%	Al2O3	1344-28-1	0.004	
			CaO	1305-78-8	1.05E-06	
			FeO2	1345-25-1	2.09E-06	
			MgO	1309-48-4	1.05E-06	
			MnO2	1313-13-9	4.19E-06	
			SiO2, amorphous	7631-86-9	6.28E-06	
			TiO2	13463-67-7	2.09E-06	
	nichrome resistor	0.0003%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	2.15E-07	
	nickel barrier	0.0004%	Ni	7440-02-0	3.36E-07	
	gold conductor	0.01%	Au	7440-57-5	7.25E-06	
	BCB passivation	0.01%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	6.88E-06	
Leadframe	copper alloy	37.1%	Cu	7440-50-8	0.028	
			Fe	7439-89-6	0.001	
			P	7723-14-0	8.58E-06	
			Zn	7440-66-6	3.43E-05	
	matte Sn plating	1.6%	Sn	7440-31-5	0.001	
	silver plating	0.9%	Ag	7440-22-4	7.30E-04	
Die adhesive	conductive epoxy	0.9%	Ag	7440-22-4	0.001	
			trade secret	unknown	1.36E-04	non-hazardous
Wire bonds	gold	0.09%	Au	7440-57-5	6.68E-05	
Molding compound	filled epoxy	53.9%	carbon black	1333-86-4	2.08E-04	
			epoxy resin, cresol novolac	29690-82-2	8.32E-04	
			SiO2, fused silica	60676-86-0	3.64E-02	
			trade secret	unknown	4.16E-03	non-hazardous
Ink marking	epoxy	0.04%	trade secret	unknown	3.30E-05	non-hazardous